

PCN20230327001.1 補足



Pls refer below as an update on this & pls note that after the PCN has expired, any of the qualified assembly sites can assemble the device/s on this PCN including the BOM listed on the PCN, thanks.

	TFME	PHI	HNA	HFTFAT	ASEWH	CDAT	TIEMA
Lead Finish	NIPDAU, MATTE SN	NIPDAU	NIPDAU, NIPDAUAG	NIPDAU	NIPDAU	MATTE SN	MATTE SN
Mount Compound	A-03 A-09	4207123	400180 A-09	A-03	1120999A2	4207123	4207123 1120999A2
Bond Wire	AU, CU	CU	AU, CU	AU, CU	AU	CU	CU
Bond Wire Diameter	20.3 UM (0.8 MIL) 25.4 UM (1.0 MIL) 33 UM (1.3 MIL)	33 UM (1.3 MIL)	15.24 UM (0.6 MIL) 20.32 UM (0.8 MIL) 25.4 UM (1.0 MIL)	25.4 UM (1.0 MIL) 33.3 UM (1.31 MIL)	25.4 UM (1.0 MIL)	20.3 UM (0.8 MIL) 25.4 UM (1.0 MIL) 33 UM (1.3 MIL)	20.3 UM (0.8 MIL) 25.4 UM (1.0 MIL) 33 UM (1.3 MIL)
Mold Compound	450207 R-17	4222198	450207 450413 450042	R-17	450207	4222198	4222198 8097131
MSL	LEVEL1-260CG LEVEL2-260CG	LEVEL2-260CG	LEVEL1-260CG LEVEL2-260CG	LEVEL1-260CG LEVEL2-260CG	LEVEL1-260CG	LEVEL1-260CG LEVEL2-260CG	LEVEL1-260CG LEVEL2-260CG
ECAT	G3 G4	G4	G4	G4	G4	G3	G3